

# **Product Change Notification - JAON-22XFVI227**

Date:

09 Jan 2020

**Product Category:** 

32-bit Microcontrollers; Touchscreen Controllers; Others

**Affected CPNs:** 



#### **Notification subject:**

CCB 3871 Final Notice: Qualification of MMT as an additional assembly site for selected Atmel products of 58.85K wafer technology available in 100L TQFP (14x14x1.0 mm) package.

#### **Notification text:**

**PCN Status:** 

Final notification

**PCN Type:** 

Manufacturing Change

### **Microchip Parts Affected:**

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

## **Description of Change:**

Qualification of MMT as an additional assembly site for selected Atmel products of 58.85K wafer technology available in 100L TQFP (14x14x1.0 mm) package.

### **Pre Change:**

Assembled at ASE assembly site using Au bond wire, CRM-1076WA die attach, G631H molding compound, C7025 lead frame material or assembled at ANAP using AuPd bond wire, 3230 die attach, G700 mold compound and C194 lead frame material.

## **Post Change:**

Assembled at ASE assembly site using Au bond wire, CRM-1076WA die attach, G631H molding compound, C7025 lead frame material or assembled at ANAP using AuPd bond wire, 3230 die attach, G700 mold compound and C194 lead frame material or assembled at MMT using Au bond wire, 3280 die attach material, G700 mold compound and C7025 lead frame material.

Pre and Post Change Summary:

Pre and Post Change Summary:										
	Pre C	hange	Post Change							
Assembly Site	Advanced Semiconductor Engineering, Inc. (ASE)	Amkor Technology Philippine (P1/P2), INC. (ANAP)	Advanced Semiconducto r Engineering, Inc. (ASE)	Philippine (P1/P2), INC. (ANAP)	Microchip Technology Thailand (MMT)					
Wire material	Au	AuPd	Au	AuPd	Au					
Die attach material	CRM-1076WA	3230	CRM-1076WA	3230	3280					
Molding compound material	G631H	G700	G631H	G700	G700					
Lead frame material	C7025	C194	C7025	C194	C7025					
MSL Level	MSL 3	MSL 3	MSL 3	MSL 3	MSL 1					
Tray Info	Bakeable Tray	Bakeable Tray	Bakeable Tray	Bakeable Tray	Non-Bakeable Tray					



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### Impacts to Data Sheet:

None

### **Change Impact:**

None

## **Reason for Change:**

To improve manufacturability and on-time delivery by qualifying MMT as an additional assembly site.

## **Change Implementation Status:**

In Progress

## **Estimated First Ship Date:**

February 9, 2020 (date code: 2007)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

### **Time Table Summary:**

	July 2019						January 2020					February 2020			
Workweek	27	28	29	30	31	^	01	02	03	04	05	06	07	80	09
Initial PCN Issue Date				X											
Qual Report															
Availability								^							
Final PCN Issue Date								X							
Estimated													<b>V</b>		
Implementation Date													^		

### Method to Identify Change:

Traceability code

### **Qualification Report:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

### **Revision History:**

July 22, 2019: Issued initial notification.

**August 13, 2019:** Re-issued initial notification to update the attached pre and post comparison file to correct the post site from MTAI to MMT

**January 9, 2020:** Issued final notification. Attached the qualification report. Provided estimated first ship date to be on February 9, 2020.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

### Attachment(s):

PCN\_JAON-22XFVI227\_Qual\_Report.pdf
PCN\_JAON-22XFVI227\_TRAY\_PRE\_AND\_POST\_CHANGE\_CCB\_3871\_rev1.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

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registering for Microchips PCN email service in the PCN FAQ section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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### Affected Catalog Part Numbers (CPN)

AT32UC3C1128C-AUR

AT32UC3C1128C-AUT

AT32UC3C1256C-AUR

AT32UC3C1256C-AURA0

AT32UC3C1256C-AUT

AT32UC3C1256C-AZR

AT32UC3C1256C-AZT

AT32UC3C1512C-AUR

AT32UC3C1512C-AUT

AT32UC3C1512C-AZR

AT32UC3C1512C-AZT

AT32UC3C164C-AUR

AT32UC3C164C-AUT

ATMXT3432S-M-AT

ATMXT3432S-M-ATR

ATMXT540E-AB

ATMXT540E-ABR

ATMXT540E-AT

ATMXT540E-ATR

ATMXT768E-AB

ATMXT768E-ABR

ATMXT768E-AT

ATMXT768E-ATR

ATMXT768EC06-AB

ATMXT768EC06-ABR

ATUC3T-ATR